



Title of Change:	Qualification of Amkor Technology Malaysia (ATM) for the Assembly and Test of Trench MOSFET packaged in SO8FL
Proposed first ship date:	29 September 2016 <i>or earlier after customer approval</i>
Contact information:	Contact your local ON Semiconductor Sales Office or GK Yeng <GuoKun.Yeng@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or Michael Mooney <Michael.Mooney@onsemi.com>
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Richard Clemente <Richard.Clemente@onsemi.com>
Type of notification:	<p>This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.</p> <p>ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.</p>
Change Part Identification:	Product from Amkor Technology Malaysia will be marked with site code YE prior to date code
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____
Change Sub-Category(s): <div style="display: flex; flex-wrap: wrap;"> <div style="width: 50%;"> <input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change </div> <div style="width: 50%;"> <input type="checkbox"/> Datasheet/Product Doc change <input checked="" type="checkbox"/> Shipping/Packaging/<u>Marking</u> <input type="checkbox"/> Other: _____ </div> </div>	
Sites Affected: <div style="display: flex; flex-wrap: wrap;"> <div style="width: 50%;"> <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : </div> <div style="width: 50%;"> <input checked="" type="checkbox"/> External Foundry/Subcon site(s) <div style="border: 1px solid black; padding: 2px; display: inline-block;">Amkor Technology Malaysia</div> </div> </div>	
Description and Purpose: <p>This Product Change Notice is to announce that ON Semiconductor is expanding assembly and test operations of SO8FL discrete packaged products, currently built at ON Semiconductor Seremban, Malaysia facility to Amkor Technology Malaysia (ATM).</p> <p>Upon the expiration of this FPCN or earlier after customer approval, Trench Mosfet devices may be processed at either location. These products have been qualified to commodity/commercial requirements. These products will continue being Pb-free, Halide free and RoHS compliant. Device quality and reliability will continue to meet ON Semiconductors high standards.</p>	

**Reliability Data Summary:**

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1008 hrs	0/ 252
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/252
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/252
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/252
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/252
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/252
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		Pass
RSH	JESD22- B106	Ta = 265°C, 10 sec		0/90
SD	JSTD002	Ta = 245°C, 10 sec		0/45

Electrical Characteristic Summary:

There is no change in electrical parametric performance. Characterization data is available upon request.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
NTMFS4C06NAT1G	NTMFS4C05NT1G
NTMFS4C10NAT1G	NTMFS4C05NT1G
NTMFS4C760NT1G	NTMFS4C05NT1G
NTMFS4C800NT1G	NTMFS4C05NT1G